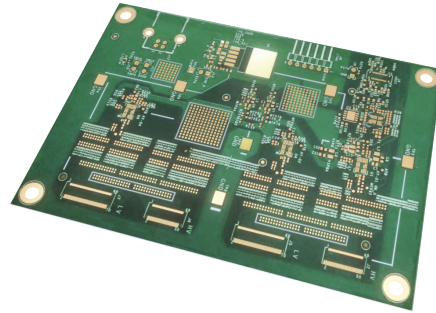


We are constantly innovating



Features	Standard	Advanced
Number of Layers	28 Layers	46 Layers
Stacked / Staggered Microvias Type	4+n+4	10+n+10
Minimum Dielectric Thickness	0.05mm	0.025mm
Minimum Copper thickness (Base)	1/3 oz	1/4 oz
Minimum Trace Width	50um (Inner Layer)	40um (Inner Layer)
	50um (Outer Layer)	40um (Outer Layer)
Minimum Trace Space	70um (Inner Layer)	40um (Inner Layer)
	70um (Outer Layer)	50um (Outer Layer)
Minimum Blind Hole Diameter	75um	50um
Aspect Ratio (Blind Hole)	0.9:1	1.3:1
Minimum Target Land Diameter	225um	175um
Minimum BGA Land/ Pad	250um	200um
Impedance Control Tolerance	±8%	±5%
Profiling Tolerance	±0.1mm	±0.075mm
Bow and Twist	≤0.5%	≤0.3%